Sponsorship & Exhibition Application Form:

Date: ________________________
Name of the company: ________________________
Postal address: ________________________
Invoice address (if different from above): ________________________
Name of the contact person: ________________________
Phone: ________________________ Fax: ________________________
E-mail: ________________________

Sponsorship
☐ Diamond Package: 1,800,000 JPY
☐ Platinum Package: 1,000,000 JPY
☐ Gold Package: 500,000 JPY

Exhibition
☐ One booth: 200,000 JPY
☐ Two booths: 400,000 JPY
☐ Three booths: 600,000 JPY
☐ Four booths: 800,000 JPY

Indicate the booth number when there is hope regarding the location.
First choice: ______________ Second choice: ______________ Third choice: ______________

Additional Sponsorship Opportunities
☐ Sponsorship of 1 Relax Area: 200,000 JPY
☐ Co-Sponsorship of Women and Young Professionals in Circuits and Systems Reception: 400,000 JPY
☐ Co-Sponsorship of Student Luncheon Meeting: 100,000 JPY
☐ Lanyard: 400,000 JPY
☐ Branded pen, notepad, or other gift: 100,000 JPY

Note:

Contact:
ISCAS 2019 Industry & Exhibition Co-Chairs
Akihiko Sugiyama (NEC Corporation)
Takayuki Nakachi (NTT)
Martins Rui (Univ. of Macau)
E-mail: exhibit@iscas2019.org